

MR1035-820



2823

#11/1
5/14/3
Sunder

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Pei Reng Jeng, et al.

Serial No. : 09/781,283

: Art Unit #2823

Filed : 13 February 2001

: Examiner:

Title : PLANARIZATION METHOD OF INTER-LAYER DIELECTRICS AND INTER-METAL DIELECTRICS

: M. Estrada

AMENDMENT

Mail Stop Non-Fee Amendment
Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED
MAY 12 2003
TECHNOLOGY CENTER 2800

Sir:

Responsive to the Official Action dated 10 February 2003, please amend the above-referenced Patent Application as follows:

IN THE CLAIMS:

Please replace Claims 1 and 9 with the "CLEAN COPY" of the amended Claims as follows:

CLEAN COPY OF AMENDED CLAIMS

1. (Four Times Amended) A planarization method of inter-layer dielectrics, comprising the steps of:

providing a semiconductor substrate including a field oxide, a source, a drain, and a gate formed thereon;

